

Product Summary

$V_{(BR)DSS}$	$R_{DS(ON) \max}$	$I_D \max$ $T_A = +25^\circ C$
30V	30mΩ @ $V_{GS} = 10V$	7.1A
	40mΩ @ $V_{GS} = 4.5V$	6.2A
	63mΩ @ $V_{GS} = 2.5V$	4.9A

Description and Applications

This MOSFET has been designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

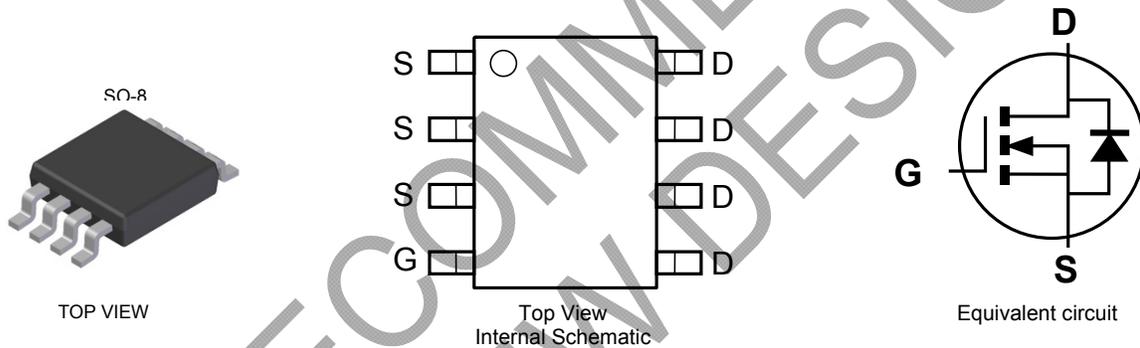
- Backlighting
- Power Management Functions
- DC-DC Converters

Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
- Terminals: Finish — Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.074 grams (approximate)

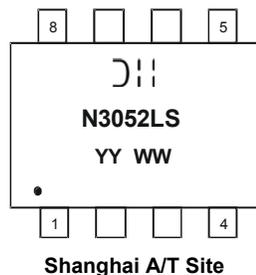
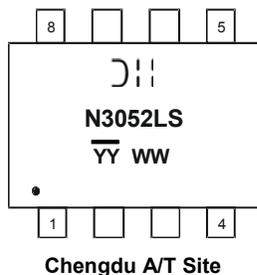


Ordering Information (Note 4)

Part Number	Case	Packaging
DMN3052LSS-13	SO-8	2500/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



- DII = Manufacturer's Marking
- N3052LS = Product Type Marking Code
- YYWW = Date Code Marking
- YY or YY = Year (ex: 13 = 2013)
- WW = Week (01 - 53)
- YY = Date Code Marking for SAT (Shanghai Assembly/ Test site)
- YY = Date Code Marking for CAT (Chengdu Assembly/ Test site)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V _{DSS}	30	V
Gate-Source Voltage			V _{GSS}	±12	V
Drain Current (Note 5)	Steady State	T _A = +25°C	I _D	7.1	A
		T _A = +70°C		5.7	
Pulsed Drain Current (Note 6)			I _{DM}	28	A

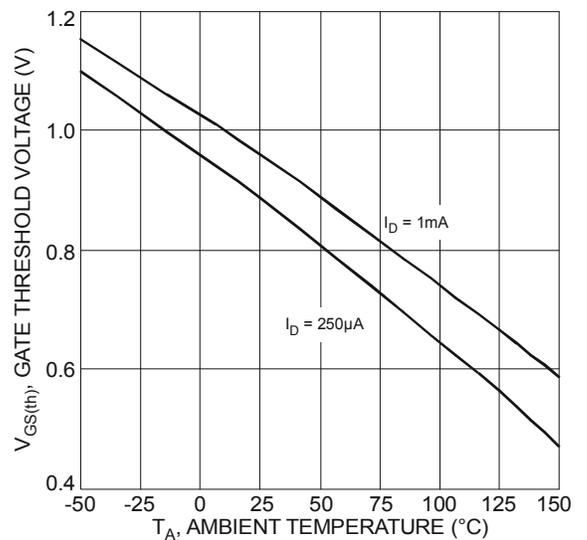
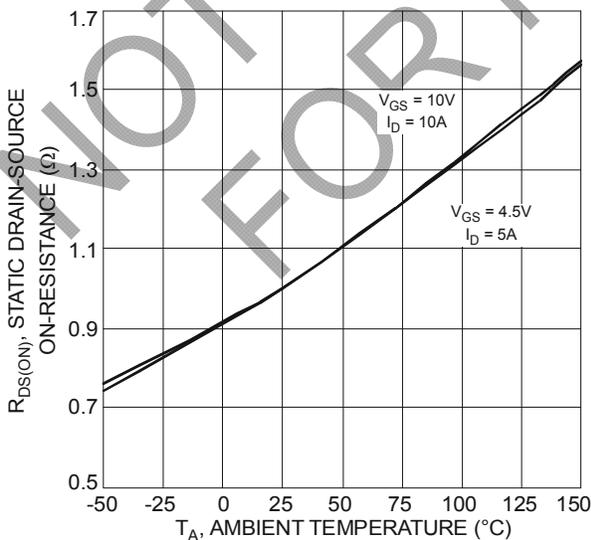
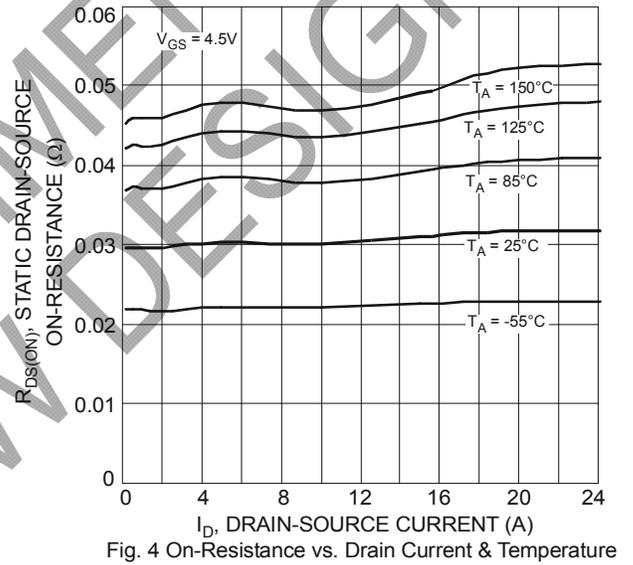
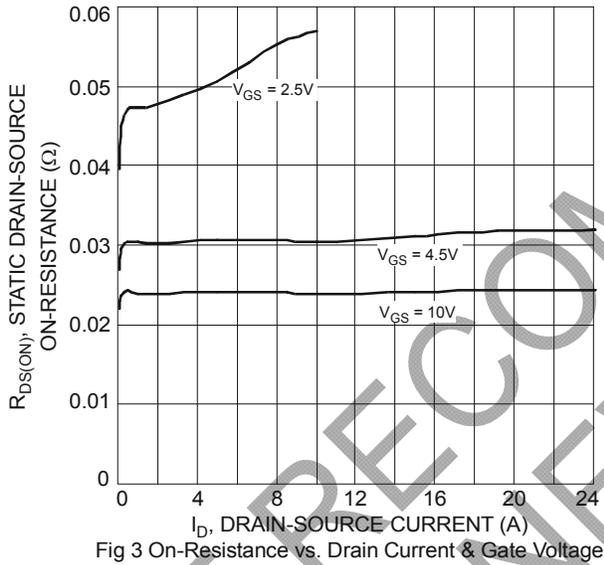
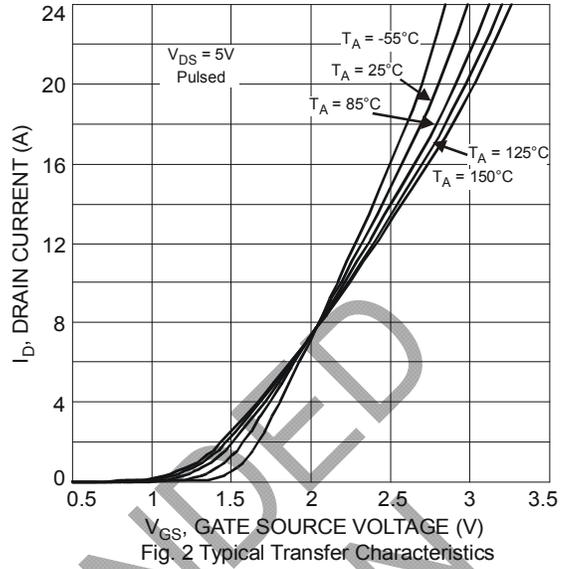
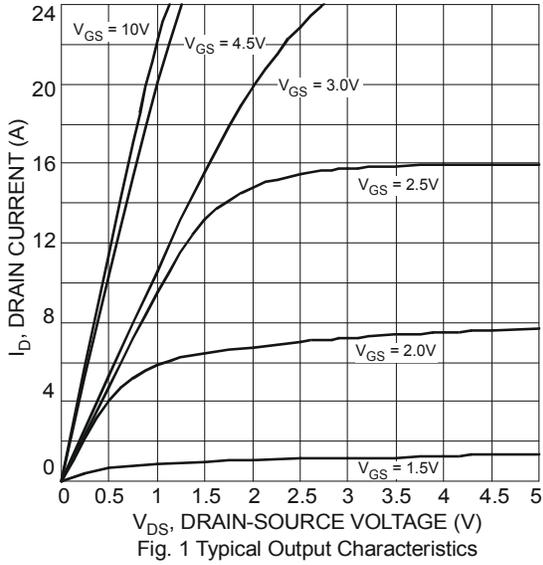
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P _D	2.5	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	50	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	30	—	—	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	μA	V _{DS} = 30V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±80 ±800	nA	V _{GS} = ±12V, V _{DS} = 0V V _{GS} = ±19V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(th)}	0.62	0.9	1.2	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	24	30	mΩ	V _{GS} = 10V, I _D = 7.1A
			30	40		V _{GS} = 4.5V, I _D = 6.4A
			50	63		V _{GS} = 2.5V, I _D = 5.0A
Forward Transconductance	g _{fs}	—	10	—	S	V _{DS} = 5V, I _D = 5.1A
Diode Forward Voltage (Note 7)	V _{SD}	—	0.78	1.16	V	V _{GS} = 0V, I _S = 2.1A
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}	—	555	—	pF	V _{DS} = 5V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oss}	—	109	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	82	—	pF	

- Notes:
5. Device mounted on 2 oz copper pad layout with R_{θJA} = 50°C/W.
 6. Pulse width ≤10μs, Duty Cycle ≤1%.
 7. Short duration pulse test used to minimize self-heating effect.



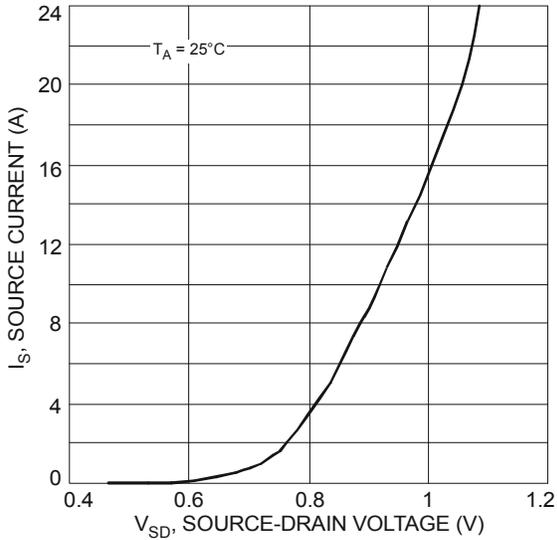


Fig. 7 Reverse Drain Current vs. Source-Drain Voltage

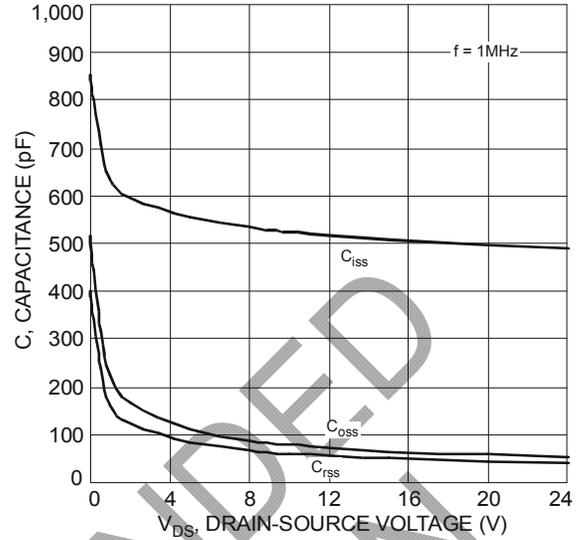


Fig. 8 Typical Total Capacitance

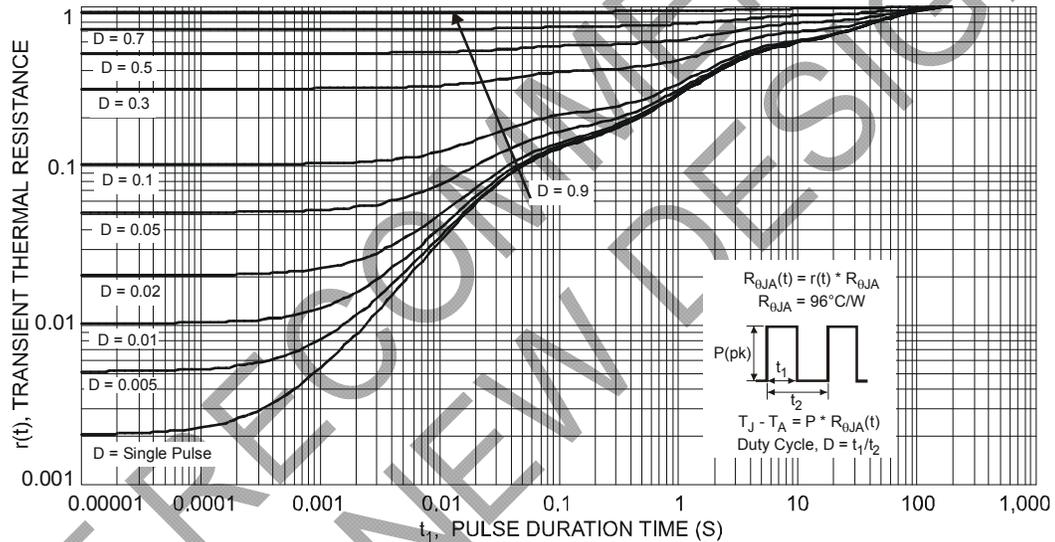
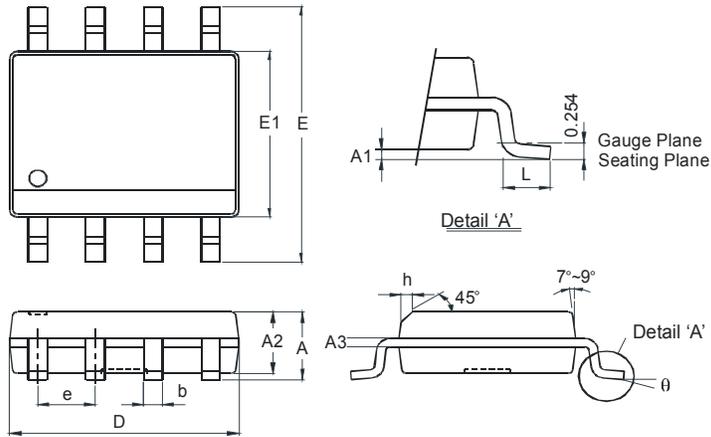


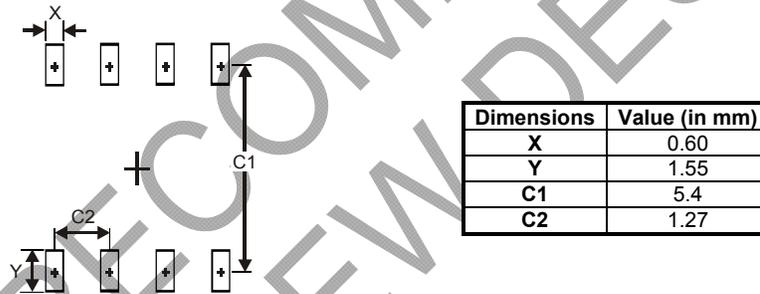
Fig. 9 Transient Thermal Resistance

Package Outline Dimensions



SO-8		
Dim	Min	Max
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	-	0.35
L	0.62	0.82
θ	0°	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

NOT RECOMMENDED FOR NEW DESIGN

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